EMBEDDED SYSTEMS

& shock

WIRELESS TECHNOLOGY

SARA-G

nodules

all 2G+3G bands

NBIOT) modules



Rugged Box PCs for automation industry Many options of I/O interfaces to find the optimal solution for the application. highest reliability because of fanless design, Watchdog built-in



Wide input voltage range Compact size

Embedded O

Dust resistant

Wide operating temperature

Strong metal housing



Perfect graphic performance, Various video output



n-vehicle computers and displays

Variety wireless communication: GPS, GSM, WLAN Flexible ignition control, easy adaption to car power-system, Railway EN50155 certificate



Machine Vision controllers Train & in-vehicle rugged computers Surveillance platforms 25 ~ 70°C extended operating temperature

Patented expansion Casette and MezIO modules

All-In-One Panel PCs with up to IP67 protection With Intel and AMD processors

Various touch options available

Embedded boards

Cost-effective reliable mini-ITX & 3.5" boards, Latest Intel Atom/Celeron/Pentium/i3/i5/i7 processors Only Japan-made high-quality Conductive Polymer Capacitors used, Min. 5 Years product availability, Various form factor Single Board Computers, Extended operating temperature

Wide range of high quality monitors

Great viewing angles and exceptional color clarity, AMVA3 / MVA / IPS panel technology with Full HD & Ultra HD resolution Projective Capacitive, Infrared or Optical Multi-Touch Technology Durable and professional design, Open frame mounting, Compatible with NEXCOM OPS players



IEXCO



Them





| PRODUCTS

rtified industrial Bluetooth modules

BT 2.1.BT 4.0 and BT 4.2 & 5.0. with medical certificates Modules with dedicated MCU for built-in applications Wi-Fi modules

Ultra compact (10x14x3.8mm) NINA-W modules, pin ompatible with Bluetooth modules



Wi-Fi, Bluetooth Dual-Mode NINA-W13 \//i_Ei

Multiradio modules

Wi-Fi. Classic BT and BT 4.0 (BLE) combined in one stand-alone module Wi-Fi (a/b/g/n/ac), Classic BT, BT 4.1 in one host module

> ODIN-W262 2.1+BT 4.0+Wi-Fi 2.4GHz & 5GHz Multiradio module 22.3x14.8mm

V2X transceiver modules

Vehicle to vehicle (V2V) and vehicle to infrastructure (V2I) wireless technology, collectively known as V2X, improves road safety, reduces traffic congestion and enhances the overall passenger experience. Positioning modules NEO-M8L, compliant to accuracy requirements under conditions. specified in recent V2X standards.

VFRA-P1 (25x30mm) Host based V2X module with AEC-Q100 and ISO 16750-4 automotive certificates



ISO Cards, Key Fobs, Wrist Bands, PET laminates RFID system solutions for: Access control. Animal indentification(Pet. bird and livestock) Industry and logistic (also KEG and waste ID)



State of the art GNSS modules based on the latest u-bloxM8/u-blox8 technology. GPS/GALILEO/Glonass/BeiDou/QZSS support

Form factors: MAX, NEO, LEA, EVA, 7OE, SAM, CAM Qualified for in vehicle use (ISO16750) High performance GNSS receivers, sensitivity: -167dBm Extremely low power: 6.6mA/1.8V (fix every 1s) Position accuracy (CEP. SBAS): < 2.0m

Built in active antenna support (power, monitor) High in-band jamming immunity, Jammer detection Odometer, Arm Swing compensation, Geofencing Assisted GNSS: for all systems

High precision NEO-M8P, accuracy < 0.025m Dedicated modules for timing, RAW data Miniature modules with built-in antenna (CAM/SAM) Built in sensors for navigation without sky view (NEO-M8L/U)

u-blox8/7/6/5 modules are pin compatik



16.0x12.2x2.4 mm 10.1x9.7x2.5 mm 7.0x7.0x1 mm 4.5x4.5x1 mm



Miniature GNSS module with Performance optimized built-in antenna (9.6x14.0x1.95mm) (15.5x15.5x6.3mm) antenna module

New u-blox F9 - multiband, next level of positioning



The u-blox F9 platform was created for reliable navigation under challenging conditions met in nowadays environment. Uses multiple bands (L1/L2/L5) to correct errors caused by the ionosphere and delivers fast TTFF.

The first modules based on u-blox F9 platform are expected in 2018.

The use of u-blox modules does not lead to consequences from infringement of patents and copyrights

NEO-M8



WIRELESS TECHNOLOGY

ELECTROMECHANICAL

Reliable, field proven GNSS and GSM/UMTS/LTE/NBIoT

High performance GSM, UMTS, LTE, NBIoT module Navigation without GPS, based on GSM network eCall ready products with in-band modem LTE low Cat (Cat.1, Cat.M1, Cat.NB1) support

> SARA-11201 - the smallest UMTS+GPRS module with worldwide band coverage

GSM/GPRS modules

Embedded TCP/UDP/IP. FTP/HTTP/SMTP stack Version with ATEX certificate Low power consumption (<0.9mA idle, 2.9mA active mode

Built-in Assisted GNSS client to support GNSS modules BIP. SSL. DTMF. SIM card detection One PCB design for GSM, UMTS, SARA-G/U

LTE (including Cat.1, Cat.M1 and NBIoT) modules or 2G+3G platf LARA-R LTE Cat. Cat.1+2G/3G SARA-U2 family of platfo GSM/UMTS/HSPA compact SARA-R LTE Cat.M1/NB1 Worldwide Form factor as small as multihand + 2G 16.0x26.0x3.0mm Economy LTE platform Worldwide version, with SARA-N TE Cat.NB1 Pin compatible to GSM, LTE

including Cat.1, Cat.M1 and

Low power consumption

Nested design available at u-blox. SARA. LARA or TOBY can be alternatively mounted on the same PCR

SARA-N2 NBIOT / LTE Cat.NB1 modules

u-blox is the market leader in development of the latest Narrow Band IoT technology

Standardized by 3GPP as LTE Cat.NB1 New Using the current GSM network (global coverage) Low power (10 years on battery) Min. 20dB better link budget than GSM (2 levels more under the ground) Long service availability (LTE bands) SARA-N2 family the first NRIoT Over 100k devices in one cell modules in accordance Dedicated to M2M, no voice, ATEX with LTE Cat.NB1 Pin compatible to GSM, UMTS, LTE (Cat.1, Cat.M1) modules

SARA-RA

LTE Cat.M1 + NB1 modules Global (multiband) design 2G/GPRS fallback

LTE technology dedicated to lower data rate applications Data rate up to 1 Mbps, CoAP, MQTT

Significant cost reduction comparing to LTE Cat.4 / Cat.1 Better link budget than GSM/LTE Cat.4 Long service availability due to LTE bands (2G/3G replacement) Pin compatible to GSM, UMTS, LTE (Cat.1, Cat.NB1/NBIoT) modules

000

MPCI family:

LTE/HSPA+/GPRS

Mini PCIe modules

I ARA-R2 LTE Cat.1 modules Data rate up to 10 Mbps

Significant cost reduction comparing I ARA family to LTE Cat.4 LTE Low Cat. modules

Version LTE Cat.1 + 2G to protect coverage Pin compatible to GSM, UMTS, LTE (Cat.M1, Cat.NB1/NBIoT) modules Pin compatible to SARA modules

TOBY-L2/L4. MPCI-L2 LTE Cat.4/6 modules. mPCI cards SSM/GPRS/HSPA+/LTE Cat.4/6 p to 300Mbps data rate

WIRELESS ACCESSORIES

GSM, GPS, GLONASS, Iridium, WiFi. ISM antennas Helical GPS & GLONASS antennas L1 & L2 band antennas IF connectors, adapter cables valuation kits and software



Reliable interconnect products

SIM / Nano SIM / Pico SIM connectors Memory Card Connectors USB Connectors Board to board connectors FFC connectors Dedicated white connectors for LED boards

DC Power Jacks

Modular Jacks



Components

Terminal Blocks. PCB mounted. pluggable and other nterconnection solutions, Fuses & Fuse-holders, Batteries, LEDs & Indicators. Miniature Switches. Limit & Safety Switches, DIN Rail mounted Interface Modules, Control Products and Transformers

Enclosures Universal Housings, Hand-held Enclosures, Die-cast

Boxes, Potting Boxes, Desktop Cases, Instrument Cases, DIN rail Enclosures or Interface Supports Full customisation service for all enclosures With custom colours, surface coating & RFI shielding, engraving & silk-screening, labels & membrane Keypads, as well as milling for

all types of connectors and control components

Custom enclosures

Designed, prototyped and manufactured to specific and exacting requirements with rapid lead-times using Flat Sheet Plastic Technology process, a solution for unique enclosure reauirements without tooling costs







HIGH DENSITY SIGNAL & POWER



Push-pull circular connectors and cable assembly solutions

Multipole Low & High Voltage connectors Coax Low & High Voltage connectors

Triax connectors Fiber optic connectors Fluid / Gas connectors Hybrid connectors



Serving all markets

From Medical to Defense From Instrumentation to Food and more

FISCHER CORE

ANY SIZE





ULTIMATE

RUGGEI COMPAC



OPTICAL PERFORM ASY CLEANING







Terminal blocks SPRINGCON - spring type RIACON - screw type PLUGCON - pin strips IDCON - IDC - PCB connectors Data communication solutions Industry RJ45 & fiberoptic connectors Ethernet M12 connectors Patch cords

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Heatsinks

Machined extruded heatsinks leatsinks for LEDs Extruded heatsinks with retaining springs for PCB mounting Heatsinks and fan coolers for processors, PGA & BGA components Cooling aggregates hermal conductive materials



Miniature aluminum cases Desk consoles and shell cases 9" system cases

Connectors

Hi precision board-to-board connectors IDC connectors D-SUB connectors DIL PGA, PLCC socket

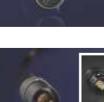


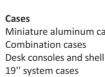
Precision CNC machining of heatsinks, cases, front panels Powder coating Screen printing YAG laser engraving

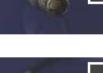














































ELECTROMECHANICAL





Industrial Cables VDE/UL/CSA/MIL approvals DIN standards Single, multiple, fine. ultra-fine wire Single, double, triple coloured Insulation: PVC/PE/TPE/silicone/ PP/PA Tefzel/Teflon/PUR/ Glass filament/EVA etc. Temperature range: -200°C to 1200°C Halogen free/flame-resistant/lead-free Customised Hybrid cables on demand



HARNESS MAKING, ASSEMBLING, MACHINES AND TOOLS



Harness making

Crimping all typical connectors, half or full automatic process Cutting and stripping from AWG32(0.05 mm²) up to AWG8 (8.00 mm² Lead free tin plating

Benchtop Crimping & Stripping

Cutting to Length & Stripping

Full Process Crimping

oiling/Collection



Hand tools for cutting and crimping

Machines for:

Marking

Prefeeding

Spare parts

Tools for various connectors

With replaceable dies

Pneumatic and manual tools for cable cutting





Wire to PCB connectors PCB to PCB connector Wire to wire connectors lumners Memory cards and PCMCIA connectors Serial, parallel, USB Wide range of terminals Strips and cables Customized harness



Automotive connectors RAST connectors 2.5 and 5.0 Chain terminals 2.8-4.8-6.3-7.7 9.3mm Ring tongue and other solderless terminals and splices Tools

Applicators Presses

for all types of connectors

Other tools & applicators for RAST connectors Applicators for: JST, LEAR, TYCO, JAE, FCI Testing tools











Pneumatic and hydraulic presses with dedicated dies

compatible with WEZAG hand tool dies





LIGHTING & SEMICONDUCTORS

LIGHTING PRODUCTS



POWER LED - super bright power LEDs. Efficacy up to 170lm/W Industry standard 3535 package. CRI 70 for streetlighting, 80 as standard and 90+ available. Horticulture dedicated red, blue and green colors in 3W and 6W

MID POWER LED - SMD | EDs in standard form factors: 5630, 3030, 3528

5630 (G7) LED efficacy up to 220lm/W (@65mA)

High flux or high efficacy 3030 packages

3528 available in various lm/\$ versions also in highly reliable and efficient Flip Chip versions

COB - from 6W up to 170W standard sized modules (13, 19, 28 mm edge), with up to 23500lm per array, and 160lm/W. Available in lateral and in Flip Chip versions

UV LED - Low, mid and high power packages. Up to 300mW in UV-C, 100mW in UV-B and 6.2W in UV-A. UV-B and UV-C wavelenghts available in the same form factor (6060)



Acrich3 - the third version of Seouls' proprietary solution. Supplied directly from 230VAC. Luminous flux of one

module up to 11500lm (105W module). and high efficacy. Modules available in many sizes for different applications.





WICOP2 - new phosphor-on-chip power Ready modules LED- small size, high power density and | High efficacy EMC packages



ESD diodes and arrays

MOSFET transistors

Voltage references

Industry standards:

many others

Amplifiers and comparators

Linear and switching voltage regulators

Historical standard and future packages:

LED drivers: DC boost, DC buck, Current Regulator

0201, 0402, 0603, 0805, 1005, 1206, 2510, SOD-923F.

SOD-723F, SOD-523F, SOD-323F, Micro SMA, SOD-123,

SMA, SMB, SMC, SMPC, SMPC 4.0, PDFN33, PDFN56,

SOT-323, SOT-363, SOT-23, SOT-25, SOT-26, SOT-223, Sub

78(9)xx. 78(9)Lxx. LM317. LM339. LM358. LM431. LM810.

SMAJ. SMBJ. SMCJ. P4KE. P6KE. 1.5KE. BAV. BAS. BAT and

TSSOP-8, SOP-8, D-PAK, D2-PAK, MBS, ABS, DBLS and many

BJT transistors

Transoptors





1 Car

10

& holders

VCXO SAW Oscillators SAW Filters

kHz Range

Oscillators

тсхо

MHz Range

RTC Modules

Gyro sensors

Programmable Oscillators

EPSON[®]

EXCEED YOUR VISION

SPXO kHz & MHz range

Timing and Sensing quartz based devices



Q

Customer specified frequency (1.000MHz to 166.000MHz) ustomer specified logic (5V. 3.3V. 2.5V. 1.8V)) sizes available including THT, SMD plastic package or SMD ceramic package Available within 24h from stock!

QUARTZ+MEMS

New Control Manager and high utilities Manager and Systems

QMEMS is a combination of 'Quartz', a crystal material with excellent characteristics such as high stability and high precision, and "MEMS" (a microfabrication technology). To a semiconductor MEMS material, EPSON applies precision microprocessing based on quartz material to create a guartz device called 'QMEMS' which offers high performance in a compact package.

Customized solutions & accessories LED modules: square and round modules in different sizes Modules based on Wicop2 LED LED strips Acrich modules Lighttubes Lenses, reflectors



Design support and contract manufacturing



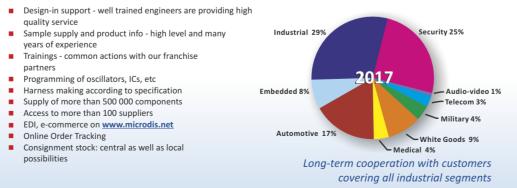
possibilities crodis.de@microdis.ne

*Electromechanical Competence Center for France

countries



SERVICES FOR OEMS AND CEMS IN EASTERN EUROPE



Supply of small quantities by catalogue distribution



The leading technical distributor of electronic components acting in Eastern Europe.

With years of experience and built up trust on the market.

Reliably providing local logistic and technical support to the most demading applications.

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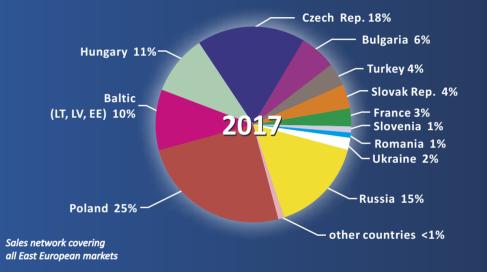
MICRODIS ELECTRONICS





MICRODIS BUSINESS MODEL

- Franchise Distribution for a selected number of manufacturers
- Special Mass Market Distribution by Internet and Catalogue
- Network Partnership with suppliers and customers



DEVELOPMENT STEPS OF THE MICRODIS ELECTRONICS GROUP

- Foundation of the companies in Hungary and Germany
- 1990 Foundation of sales companies in Poland and Slovakia
- 1992 Foundation of LSB Electronics later renamed to Microdis Plus Poland Restructuring from retail to distribution
- 1993 Foundation of Microdis KFT in Hungary
- 1995 Consolidation of all companies within the Eurodis Microdis Holding AG in Switzerland (60% Eurodis [later Eurodis Electron PLC] and 40% Microdis) Foundation of a subsidiary in Czech Republic
- 2000 Europartners Consultants proclaimed Eurodis Microdis No. 1 in Poland and No. 3 in Hungary. Start of catalogue distribution
- 2003 Microdis sells its 40% shares of the Eurodis Microdis Electronics AG to Eurodis Electron PLC and takes over entirely Eurodis Microdis Electronics in Germany
- 2006 Microdis obtained ISO 9001:2000 Certification
- 2008 Foundation of Microdis in Latvia
- 2009 Foundation of Microdis in Bulgaria
- 2010 Microdis Group obtained ISO 9001/2008 Certification
- 2011 Foundation of Microdis Components Elektronik in Turkey (Istanbul
- 2012 Purchase and Customer Service moved to the acquired building in Hockenheim, Germany
- 2013 Inauguration of Electromechanical Competence Center for France, in Sarrebruck
- 2014 25 years of Microdis' Innovation and Reliability on the market
- 2017 Official opening of our property in Zerniki Wroclawskie, Poland Relocation of Microdis Logistic Center to our new building

µ Microdis

Innovation & Reliability

ADVANCED EDI SYSTEM

- Access to components base with individual, quantity dependent, pricing
- Stock information
- Downloadable file with components base
- On-line ordering
- Order status and order/invoice history information
- Individual account for each employee





ME Żerniki Wrocławskie, Polano



ME Hockenheim, Germa

www.microdis.net